

| External_Type  | Material_Group | Substances   | CAS_Number | Mass            | Mass_Percentage_in_Leaf | Massmg        |
|----------------|----------------|--|------------|-----------------|-------------------------|---------------|
| Die            | Doped silicon  | Silicon (Si)   | 7440-21-3  | 1.05            | 100.0                   | 3.6           |
|                |                |  |            | <b>Subtotal</b> | <b>1.05</b>             | <b>100</b>    |
| Post-plating   | Pure metal     | Tin (Sn)   | 7440-31-5  | 3.51            | 100.0                   | 12            |
|                |                |  |            | <b>Subtotal</b> | <b>3.51</b>             | <b>100</b>    |
| Lead Frame     | Copper alloy   | Phosphorous (P)  | 7723-14-0  | 0.02            | 0.03                    | 0.05          |
|                | Copper alloy   | Nickel (Ni) - cas no. 7440-02-0                        | 7440-02-0  | 0.02            | 0.03                    | 0.05          |
|                | Copper alloy   | Iron (Fe)  | 7439-89-6  | 0.05            | 0.1                     | 0.17          |
|                | Copper alloy   | Copper (Cu)  | 7440-50-8  | 50.92           | 99.84                   | 173.92        |
|                |                |  |            | <b>Subtotal</b> | <b>51.01</b>            | <b>100</b>    |
| Mould Compound | Polymer        | Phenol Formaldehyde resin (generic)                    | 9003-35-4  | 2.62            | 6.0                     | 8.96          |
|                | Polymer        | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.06            | 7.0                     | 10.45         |
|                | Filler         | Silica fused   | 60676-86-0 | 37.59           | 86.0                    | 128.4         |
|                | Carbon Black   | Carbon black   | 1333-86-4  | 0.44            | 1.0                     | 1.49          |
|                |                |  |            | <b>Subtotal</b> | <b>43.71</b>            | <b>100</b>    |
| Wire           | Pure metal     | Aluminium (Al)   | 7429-90-5  | 0.04            | 100.0                   | 0.15          |
|                | Pure metal     | Aluminium (Al)   | 7429-90-5  | 0.15            | 100.0                   | 0.5           |
|                |                |  |            | <b>Subtotal</b> | <b>0.19</b>             | <b>200</b>    |
| Die Attach     | Lead alloy     | Tin (Sn)   | 7440-31-5  | 0.01            | 2.0                     | 0.04          |
|                | Lead alloy     | Silver (Ag)  | 7440-22-4  | 0.01            | 2.5                     | 0.05          |
|                | Lead alloy     | Lead (Pb)  | 7439-92-1  | 0.51            | 95.5                    | 1.74          |
|                |                |  |            | <b>Subtotal</b> | <b>0.53</b>             | <b>100</b>    |
|                |                |  |            | <b>Total</b>    | <b>100</b>              | <b>100</b>    |
|                |                |  |            |                 |                         | <b>341.57</b> |

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